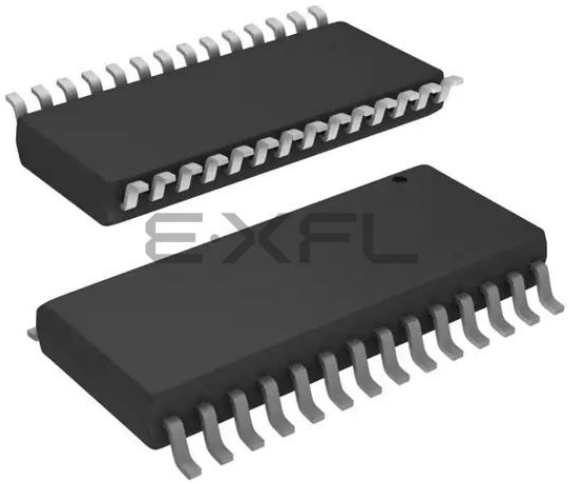
Microchip Technology - DSPIC33FJ16GS402-E/SO Datasheet



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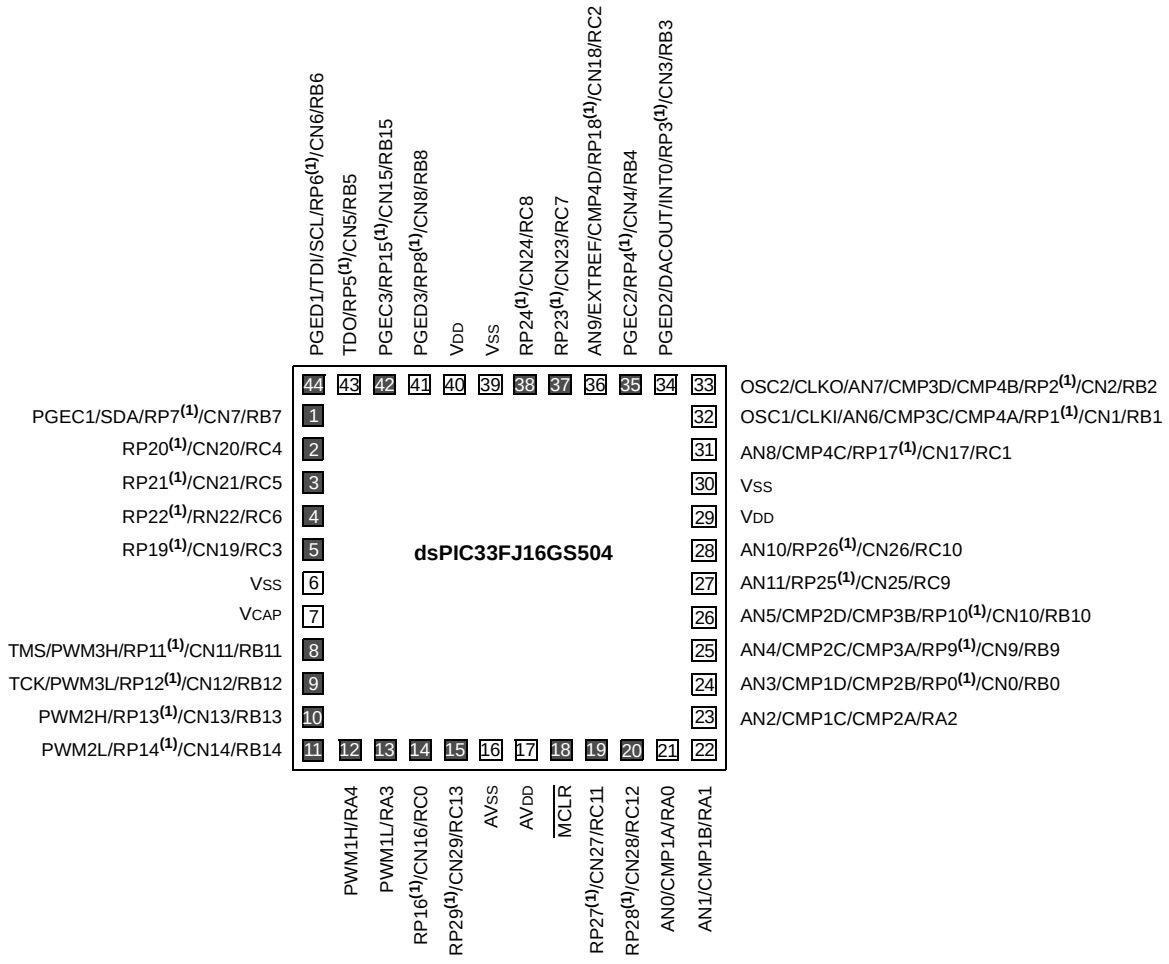
Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	21
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj16gs402-e-so

Pin Diagrams (Continued)

44-Pin VTLA(2)

■ = Pins are up to 5V tolerant



Note 1: The RPn pins can be used by any remappable peripheral. See **Table 1** for the list of available peripherals.

2: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

3.4 CPU Control Registers

REGISTER 3-1: SR: CPU STATUS REGISTER

R-0	R-0	R/C-0	R/C-0	R-0	R/C-0	R-0	R/W-0
OA	OB	SA(1)	SB(1)	OAB	SAB(1,4)	DA	DC
bit 15							bit 8

R/W-0(3)	R/W-0(3)	R/W-0(3)	R-0	R/W-0	R/W-0	R/W-0	R/W-0
IPL2(2)	IPL1(2)	IPL0(2)	RA	N	OV	Z	C
bit 7							bit 0

Legend:	C = Clearable bit		
R = Readable bit	W = Writable bit	-n = Value at POR	'1' = Bit is set
0' = Bit is cleared	'x = Bit is unknown	U = Unimplemented bit, read as '0'	

bit 15 **OA:** Accumulator A Overflow Status bit
1 = Accumulator A has overflowed
0 = Accumulator A has not overflowed

bit 14 **OB:** Accumulator B Overflow Status bit
1 = Accumulator B has overflowed
0 = Accumulator B has not overflowed

bit 13 **SA:** Accumulator A Saturation 'Sticky' Status bit(1)
1 = Accumulator A is saturated or has been saturated at some time
0 = Accumulator A is not saturated

bit 12 **SB:** Accumulator B Saturation 'Sticky' Status bit(1)
1 = Accumulator B is saturated or has been saturated at some time
0 = Accumulator B is not saturated

bit 11 **OAB:** OA || OB Combined Accumulator Overflow Status bit
1 = Accumulator A or B has overflowed
0 = Neither Accumulator A or B has overflowed

bit 10 **SAB:** SA || SB Combined Accumulator 'Sticky' Status bit(1,4)
1 = Accumulator A or B is saturated or has been saturated at some time in the past
0 = Neither Accumulator A or B is saturated

bit 9 **DA:** DO Loop Active bit
1 = DO loop in progress
0 = DO loop not in progress

bit 8 **DC:** MCU ALU Half Carry/$\overline{\text{Borrow}}$ bit
1 = A carry-out from the 4th low-order bit (for byte-sized data) or 8th low-order bit (for word-sized data) of the result occurred
0 = No carry-out from the 4th low-order bit (for byte-sized data) or 8th low-order bit (for word-sized data) of the result occurred

Note 1: This bit can be read or cleared (not set).

2: The IPL<2:0> bits are concatenated with the IPL<3> bit (CORCON<3>) to form the CPU Interrupt Priority Level (IPL). The value in parentheses indicates the IPL if IPL<3> = 1. User interrupts are disabled when IPL<3> = 1.

3: The IPL<2:0> Status bits are read-only when NSTDIS = 1 (INTCON1<15>).

4: Clearing this bit will clear SA and SB.

TABLE 4-45: PMD REGISTER MAP FOR dsPIC33FJ06GS202 DEVICES ONLY

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PMD1	0770	—	—	—	T2MD	T1MD	—	PWMMD	—	I2C1MD	—	U1MD	—	SPI1MD	—	—	ADCMD	0000
PMD2	0772	—	—	—	—	—	—	—	IC1MD	—	—	—	—	—	—	—	OC1MD	0000
PMD3	0774	—	—	—	—	—	CMPMD	—	—	—	—	—	—	—	—	—	—	0000
PMD4	0776	—	—	—	—	—	—	—	—	—	—	—	—	REFOMD	—	—	—	0000
PMD6	077A	—	—	—	—	—	—	PWM2MD	PWM1MD	—	—	—	—	—	—	—	—	0000
PMD7	077C	—	—	—	—	—	—	CMP2MD	CMP1MD	—	—	—	—	—	—	—	—	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-46: PMD REGISTER MAP FOR dsPIC33FJ16GS402 AND dsPIC33FJ16GS404 DEVICES ONLY

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PMD1	0770	—	—	T3MD	T2MD	T1MD	—	PWMMD	—	I2C1MD	—	U1MD	—	SPI1MD	—	—	ADCMD	0000
PMD2	0772	—	—	—	—	—	—	IC2MD	IC1MD	—	—	—	—	—	—	OC2MD	OC1MD	0000
PMD3	0774	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
PMD4	0776	—	—	—	—	—	—	—	—	—	—	—	—	REFOMD	—	—	—	0000
PMD6	077A	—	—	—	—	—	PWM3MD	PWM2MD	PWM1MD	—	—	—	—	—	—	—	—	0000
PMD7	077C	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-47: PMD REGISTER MAP FOR dsPIC33FJ16GS502 AND dsPIC33FJ16GS504 DEVICES ONLY

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PMD1	0770	—	—	T3MD	T2MD	T1MD	—	PWMMD	—	I2C1MD	—	U1MD	—	SPI1MD	—	—	ADCMD	0000
PMD2	0772	—	—	—	—	—	—	IC2MD	IC1MD	—	—	—	—	—	—	OC2MD	OC1MD	0000
PMD3	0774	—	—	—	—	—	CMPMD	—	—	—	—	—	—	—	—	—	—	0000
PMD4	0776	—	—	—	—	—	—	—	—	—	—	—	—	REFOMD	—	—	—	0000
PMD6	077A	—	—	—	—	PWM4MD	PWM3MD	PWM2MD	PWM1MD	—	—	—	—	—	—	—	—	0000
PMD7	077C	—	—	—	—	CMP4MD	CMP3MD	CMP2MD	CMP1MD	—	—	—	—	—	—	—	—	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

4.4.3 MODULO ADDRESSING APPLICABILITY

Modulo Addressing can be applied to the Effective Address (EA) calculation associated with any W register. Address boundaries check for addresses equal to:

- The upper boundary addresses for incrementing buffers
- The lower boundary addresses for decrementing buffers

The address boundaries check for addresses less than or greater than the upper (for incrementing buffers) and lower (for decrementing buffers) boundary addresses (not just equal to). Address changes can, therefore, jump beyond boundaries and still be adjusted correctly.

Note:	The modulo corrected Effective Address is written back to the register only when Pre-Modify or Post-Modify Addressing mode is used to compute the Effective Address. When an address offset (such as [W7 + W2]) is used, Modulo Addressing correction is performed but the contents of the register remain unchanged.

4.5 Bit-Reversed Addressing

Bit-Reversed Addressing mode is intended to simplify data re-ordering for radix-2 FFT algorithms. It is supported by the X AGU for data writes only.

The modifier, which can be a constant value or register contents, is regarded as having its bit order reversed. The address source and destination are kept in normal order. Thus, the only operand requiring reversal is the modifier.

4.5.1 BIT-REVERSED ADDRESSING IMPLEMENTATION

Bit-Reversed Addressing mode is enabled in any of these situations:

- BWM bits (W register selection) in the MODCON register are any value other than 15 (the stack cannot be accessed using Bit-Reversed Addressing)
- The BREN bit is set in the XBREV register
- The addressing mode used is Register Indirect with Pre-Increment or Post-Increment

If the length of a bit-reversed buffer is $M = 2^N$ bytes, the last 'N' bits of the data buffer start address must be zeros.

XB<14:0> is the Bit-Reversed Address modifier, or 'pivot point,' which is typically a constant. In the case of an FFT computation, its value is equal to half of the FFT data buffer size.

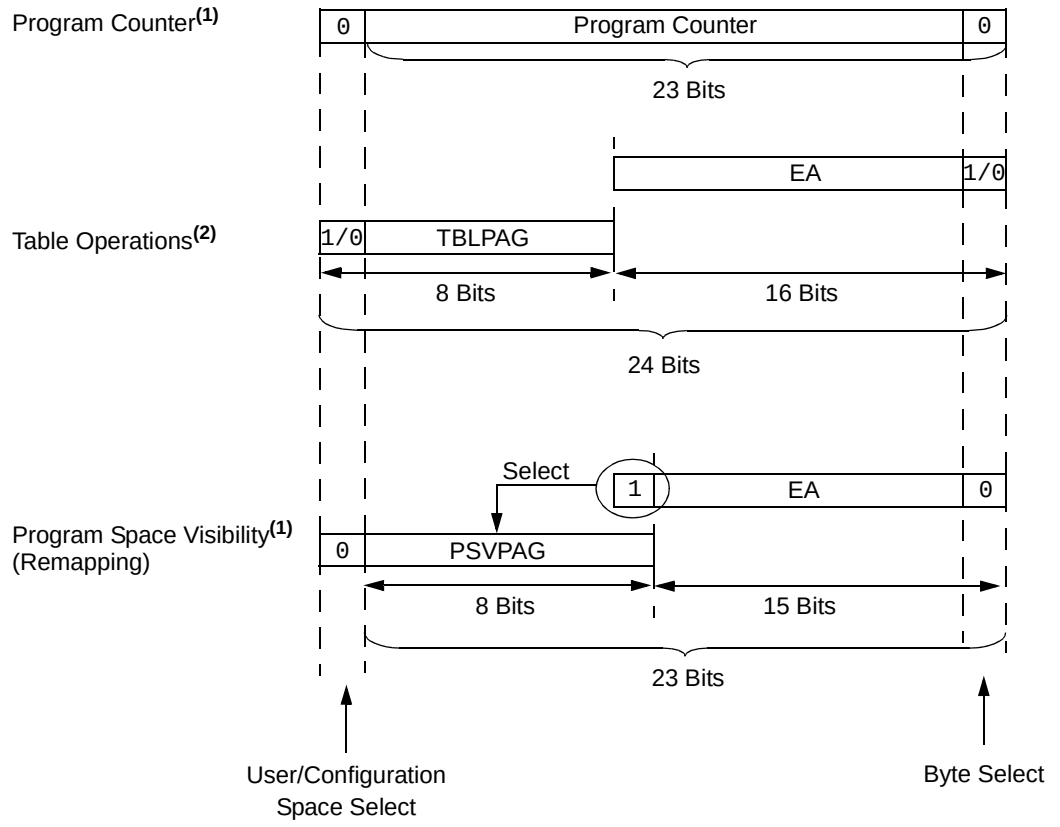
Note:	All bit-reversed EA calculations assume word-sized data (LSb of every EA is always clear). The XB value is scaled accordingly to generate compatible (byte) addresses.

When enabled, Bit-Reversed Addressing is executed only for Register Indirect with Pre-Increment or Post-Increment Addressing and word-sized data writes. It will not function for any other addressing mode or for byte-sized data, and normal addresses are generated instead. When Bit-Reversed Addressing is active, the W Address Pointer is always added to the address modifier (XB), and the offset associated with the Register Indirect Addressing mode is ignored. In addition, as word-sized data is a requirement, the LSb of the EA is ignored (and always clear).

Note:	Modulo Addressing and Bit-Reversed Addressing should not be enabled together. If an application attempts to do so, Bit-Reversed Addressing will assume priority when active for the X WAGU and X WAGU; Modulo Addressing will be disabled. However, Modulo Addressing will continue to function in the X RAGU.

If Bit-Reversed Addressing has already been enabled by setting the BREN (XBREV<15>) bit, a write to the XBREV register should not be immediately followed by an indirect read operation using the W register that has been designated as the Bit-Reversed Pointer.

FIGURE 4-9: DATA ACCESS FROM PROGRAM SPACE ADDRESS GENERATION



Note 1: The Least Significant bit (LSb) of program space addresses is always fixed as '0' to maintain word alignment of data in the program and data spaces.

2: Table operations are not required to be word-aligned. Table Read operations are permitted in the configuration memory space.

REGISTER 7-3: INTCON1: INTERRUPT CONTROL REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
NSTDIS	OVAERR	OVBERR	COVAERR	COVBERR	OVATE	OVBTE	COVTE
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0
SFTACERR	DIV0ERR	—	MATHERR	ADDRERR	STKERR	OSCFAIL	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **NSTDIS:** Interrupt Nesting Disable bit
1 = Interrupt nesting is disabled
0 = Interrupt nesting is enabled

bit 14 **OVAERR:** Accumulator A Overflow Trap Flag bit
1 = Trap was caused by overflow of Accumulator A
0 = Trap was not caused by overflow of Accumulator A

bit 13 **OVBERR:** Accumulator B Overflow Trap Flag bit
1 = Trap was caused by overflow of Accumulator B
0 = Trap was not caused by overflow of Accumulator B

bit 12 **COVAERR:** Accumulator A Catastrophic Overflow Trap Flag bit
1 = Trap was caused by catastrophic overflow of Accumulator A
0 = Trap was not caused by catastrophic overflow of Accumulator A

bit 11 **COVBERR:** Accumulator B Catastrophic Overflow Trap Flag bit
1 = Trap was caused by catastrophic overflow of Accumulator B
0 = Trap was not caused by catastrophic overflow of Accumulator B

bit 10 **OVATE:** Accumulator A Overflow Trap Enable bit
1 = Trap overflow of Accumulator A
0 = Trap is disabled

bit 9 **OVBTE:** Accumulator B Overflow Trap Enable bit
1 = Trap overflow of Accumulator B
0 = Trap is disabled

bit 8 **COVTE:** Catastrophic Overflow Trap Enable bit
1 = Trap on catastrophic overflow of Accumulator A or B enabled
0 = Trap is disabled

bit 7 **SFTACERR:** Shift Accumulator Error Status bit
1 = Math error trap was caused by an invalid accumulator shift
0 = Math error trap was not caused by an invalid accumulator shift

bit 6 **DIV0ERR:** Arithmetic Error Status bit
1 = Math error trap was caused by a divide-by-zero
0 = Math error trap was not caused by a divide-by-zero

bit 5 **Unimplemented:** Read as ‘0’

bit 4 **MATHERR:** Arithmetic Error Status bit
1 = Math error trap has occurred
0 = Math error trap has not occurred

bit 3 **ADDRERR:** Address Error Trap Status bit
1 = Address error trap has occurred
0 = Address error trap has not occurred

REGISTER 7-18: IEC7: INTERRUPT ENABLE CONTROL REGISTER 7

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	ADCP6IE	ADCP5IE	ADCP4IE	ADCP3IE	ADCP2IE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-5 **Unimplemented:** Read as ‘0’

bit 4 **ADCP6IE:** ADC Pair 6 Conversion Done Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 3 **ADCP5IE:** ADC Pair 5 Conversion Done Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 2 **ADCP4IE:** ADC Pair 4 Conversion Done Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 1 **ADCP3IE:** ADC Pair 3 Conversion Done Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 0 **ADCP2IE:** ADC Pair 2 Conversion Done Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

8.1.3 PLL CONFIGURATION

The primary oscillator and internal FRC oscillator can optionally use an on-chip PLL to obtain higher speeds of operation. The PLL provides significant flexibility in selecting the device operating speed. A block diagram of the PLL is shown in Figure 8-2.

The output of the primary oscillator or FRC, denoted as 'FIN', is divided down by a prescale factor (N1) of 2, 3, ... or 33 before being provided to the PLL's Voltage Controlled Oscillator (VCO). The input to the VCO must be selected in the range of 0.8 MHz to 8 MHz. The prescale factor 'N1' is selected using the PLLPRE<4:0> bits (CLKDIV<4:0>).

The PLL Feedback Divisor, selected using the PLLDIV<8:0> bits (PLLFBD<8:0>), provides a factor, 'M', by which the input to the VCO is multiplied. This factor must be selected such that the resulting VCO output frequency is in the range of 100 MHz to 200 MHz.

The VCO output is further divided by a postscale factor, 'N2'. This factor is selected using the PLLPOST<1:0> bits (CLKDIV<7:6>). 'N2' can be either 2, 4, or 8, and must be selected such that the PLL output frequency (FOSC) is in the range of 12.5 MHz to 80 MHz, which generates device operating speeds of 6.25-40 MIPS.

For a primary oscillator or FRC oscillator, output 'FIN', the PLL output 'FOSC' is given by Equation 8-2.

EQUATION 8-2: FOSC CALCULATION

$$FOSC = FIN * \left(\frac{M}{N1*N2}\right)$$

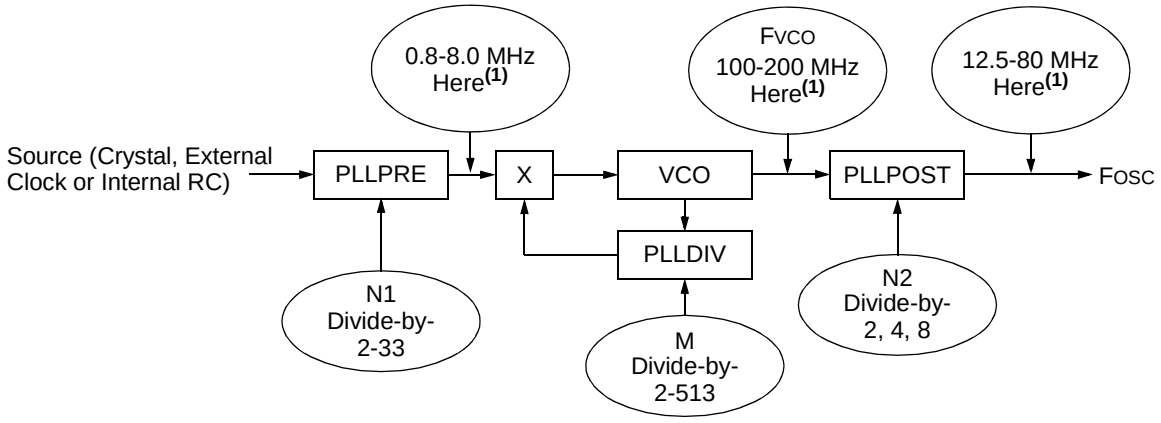
For example, suppose a 10 MHz crystal is being used with the selected oscillator mode of XT with PLL (see Equation 8-3).

- If PLLPRE<4:0> = 0, then N1 = 2. This yields a VCO input of 10/2 = 5 MHz, which is within the acceptable range of 0.8-8 MHz.
- If PLLDIV<8:0> = 0x1E, then M = 32. This yields a VCO output of 5 x 32 = 160 MHz, which is within the 100-200 MHz ranged needed.
- If PLLPOST<1:0> = 0, then N2 = 2. This provides a Fosc of 160/2 = 80 MHz. The resultant device operating speed is 80/2 = 40 MIPS.

EQUATION 8-3: XT WITH PLL MODE EXAMPLE

$$FCY = \frac{FOSC}{2} = \frac{1}{2}\left(\frac{10000000 * 32}{2 * 2}\right) = 40 \text{ MIPS}$$

FIGURE 8-2: dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04 PLL BLOCK DIAGRAM



Note 1: This frequency range must be satisfied at all times.

REGISTER 8-6: REFOCON: REFERENCE OSCILLATOR CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ROON	—	ROSSLP	ROSEL	RODIV3(1)	RODIV2(1)	RODIV1(1)	RODIV0(1)
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ROON:** Reference Oscillator Output Enable bit
1 = Reference oscillator output is enabled on the REFCLK0 pin(2)
0 = Reference oscillator output is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **ROSSLP:** Reference Oscillator Run in Sleep bit
1 = Reference oscillator output continues to run in Sleep
0 = Reference oscillator output is disabled in Sleep

bit 12 **ROSEL:** Reference Oscillator Source Select bit
1 = Oscillator crystal is used as the reference clock
0 = System clock is used as the reference clock

bit 11-8 **RODIV<3:0>:** Reference Oscillator Divider bits(1)
1111 = Reference clock divided by 32,768
1110 = Reference clock divided by 16,384
1101 = Reference clock divided by 8,192
1100 = Reference clock divided by 4,096
1011 = Reference clock divided by 2,048
1010 = Reference clock divided by 1,024
1001 = Reference clock divided by 512
1000 = Reference clock divided by 256
0111 = Reference clock divided by 128
0110 = Reference clock divided by 64
0101 = Reference clock divided by 32
0100 = Reference clock divided by 16
0011 = Reference clock divided by 8
0010 = Reference clock divided by 4
0001 = Reference clock divided by 2
0000 = Reference clock

bit 7-0 **Unimplemented:** Read as '0'

Note 1: The reference oscillator output must be disabled (ROON = 0) before writing to these bits.
2: This pin is remappable. Refer to **Section 10.6 "Peripheral Pin Select"** for more information.

TABLE 10-1: SELECTABLE INPUT SOURCES (MAPS INPUT TO FUNCTION)

Input Name	Function Name	Register	Configuration Bits
External Interrupt 1	INT1	RPINR0	INT1R<5:0>
External Interrupt 2	INT2	RPINR1	INT2R<5:0>
Timer1 External Clock	T1CK	RPINR2	T1CKR<5:0>
Timer2 External Clock	T2CK	RPINR3	T2CKR<5:0>
Timer3 External Clock	T3CK	RPINR3	T3CKR<5:0>
Input Capture 1	IC1	RPINR7	IC1R<5:0>
Input Capture 2	IC2	RPINR7	IC2R<5:0>
Output Compare Fault A	OCFA	RPINR11	OCFAR<5:0>
UART1 Receive	U1RX	RPINR18	U1RXR<5:0>
UART1 Clear-to-Send	$\overline{\text{U1CTS}}$	RPINR18	U1CTSR<5:0>
SPI Data Input 1	SDI1	RPINR20	SDI1R<5:0>
SPI Clock Input 1	SCK1	RPINR20	SCK1R<5:0>
SPI Slave Select Input 1	$\overline{\text{SS1}}$	RPINR21	SS1R<5:0>
PWM Fault Input PWM1	FLT1	RPINR29	FLT1R<5:0>
PWM Fault Input PWM2	FLT2	RPINR30	FLT2R<5:0>
PWM Fault Input PWM3	FLT3	RPINR30	FLT3R<5:0>
PWM Fault Input PWM4	FLT4	RPINR31	FLT4R<5:0>
PWM Fault Input PWM5	FLT5	RPINR31	FLT5R<5:0>
PWM Fault Input PWM6	FLT6	RPINR32	FLT6R<5:0>
PWM Fault Input PWM7	FLT7	RPINR32	FLT7R<5:0>
PWM Fault Input PWM8	FLT8	RPINR33	FLT8R<5:0>
External Synchronization signal to PWM Master Time Base	SYNCI1	RPINR33	SYNCI1R<5:0>
External Synchronization signal to PWM Master Time Base	SYNCI2	RPINR34	SYNCI2R<5:0>

10.6.2.3 Virtual Pins

dsPIC33FJ06GS101/X02 and dsPIC33FJ16GSX02/X04 devices support four virtual RPn pins (RP32, RP33, RP34 and RP35), which are identical in functionality to all other RPn pins, with the exception of pinouts. These four pins are internal to the devices and are not connected to a physical device pin.

These pins provide a simple way for inter-peripheral connection without utilizing a physical pin. For example, the output of the analog comparator can be connected to RP32 and the PWM Fault input can be configured for RP32 as well. This configuration allows the analog comparator to trigger PWM Faults without the use of an actual physical pin on the device.

10.6.3 CONTROLLING CONFIGURATION CHANGES

Because peripheral remapping can be changed during run time, some restrictions on peripheral remapping are needed to prevent accidental configuration changes. dsPIC33F devices include three features to prevent alterations to the peripheral map:

- Control register lock sequence
- Continuous state monitoring
- Configuration bit pin select lock

10.6.3.1 Control Register Lock

Under normal operation, writes to the RPINRx and RPORx registers are not allowed. Attempted writes appear to execute normally, but the contents of the registers remain unchanged. To change these registers, they must be unlocked in hardware. The register lock is controlled by the IOLOCK bit (OSCCON<6>). Setting IOLOCK prevents writes to the control registers; clearing IOLOCK allows writes.

To set or clear IOLOCK, a specific command sequence must be executed:

1. Write 0x46 to OSCCON<7:0>.
2. Write 0x57 to OSCCON<7:0>.
3. Clear (or set) IOLOCK as a single operation.

Note: MPLAB® C30 provides built-in C language functions for unlocking the OSCCON register:

```
__builtin_write_OSCCONL(value)
__builtin_write_OSCCONH(value)
```

See the MPLAB C30 Help files for more information.

Unlike the similar sequence with the oscillator's LOCK bit, IOLOCK remains in one state until changed. This allows all of the Peripheral Pin Selects to be configured with a single unlock sequence followed by an update to all control registers, then locked with a second lock sequence.

10.6.3.2 Continuous State Monitoring

In addition to being protected from direct writes, the contents of the RPINRx and RPORx registers are constantly monitored in hardware by shadow registers. If an unexpected change in any of the registers occurs (such as cell disturbances caused by ESD or other external events), a Configuration Mismatch Reset will be triggered.

10.6.3.3 Configuration Bit Pin Select Lock

As an additional level of safety, the device can be configured to prevent many write session to the RPINRx and RPORx registers. The IOL1WAY (FOSC<5>) Configuration bit blocks the IOLOCK bit from being cleared after it has been set once. If IOLOCK remains set, the register unlock procedure will not execute and the Peripheral Pin Select Control registers cannot be written to. The only way to clear the bit and re-enable peripheral remapping is to perform a device Reset.

In the default (unprogrammed) state, IOL1WAY is set, restricting users to one write session. Programming IOL1WAY allows user applications unlimited access (with the proper use of the unlock sequence) to the Peripheral Pin Select registers.

REGISTER 10-7: RPINR20: PERIPHERAL PIN SELECT INPUT REGISTER 20

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	SCK1R5	SCK1R4	SCK1R3	SCK1R2	SCK1R1	SCK1R0
bit 15							bit 8

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	SDI1R5	SDI1R4	SDI1R3	SDI1R2	SDI1R1	SDI1R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **SCK1R<5:0>:** Assign SPI1 Clock Input (SCK1IN) to the Corresponding RPn Pin bits

111111 = Input tied to Vss
100011 = Input tied to RP35
100010 = Input tied to RP34
100001 = Input tied to RP33
100000 = Input tied to RP32
•
•
•
00000 = Input tied to RP0

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **SDI1R<5:0>:** Assign SPI1 Data Input (SDI1) to the Corresponding RPn Pin bits

111111 = Input tied to Vss
100011 = Input tied to RP35
100010 = Input tied to RP34
100001 = Input tied to RP33
100000 = Input tied to RP32
•
•
•
00000 = Input tied to RP0

REGISTER 14-1: OCxCON: OUTPUT COMPARE x CONTROL REGISTER (x = 1, 2)

U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
—	—	OCSIDL	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R-0, HC	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	OCFLT	OCTSEL	OCM2	OCM1	OCM0
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13 **OCSIDL:** Stop Output Compare in Idle Mode Control bit
1 = Output Compare x halts in CPU Idle mode
0 = Output Compare x continues to operate in CPU Idle mode

bit 12-5 **Unimplemented:** Read as '0'

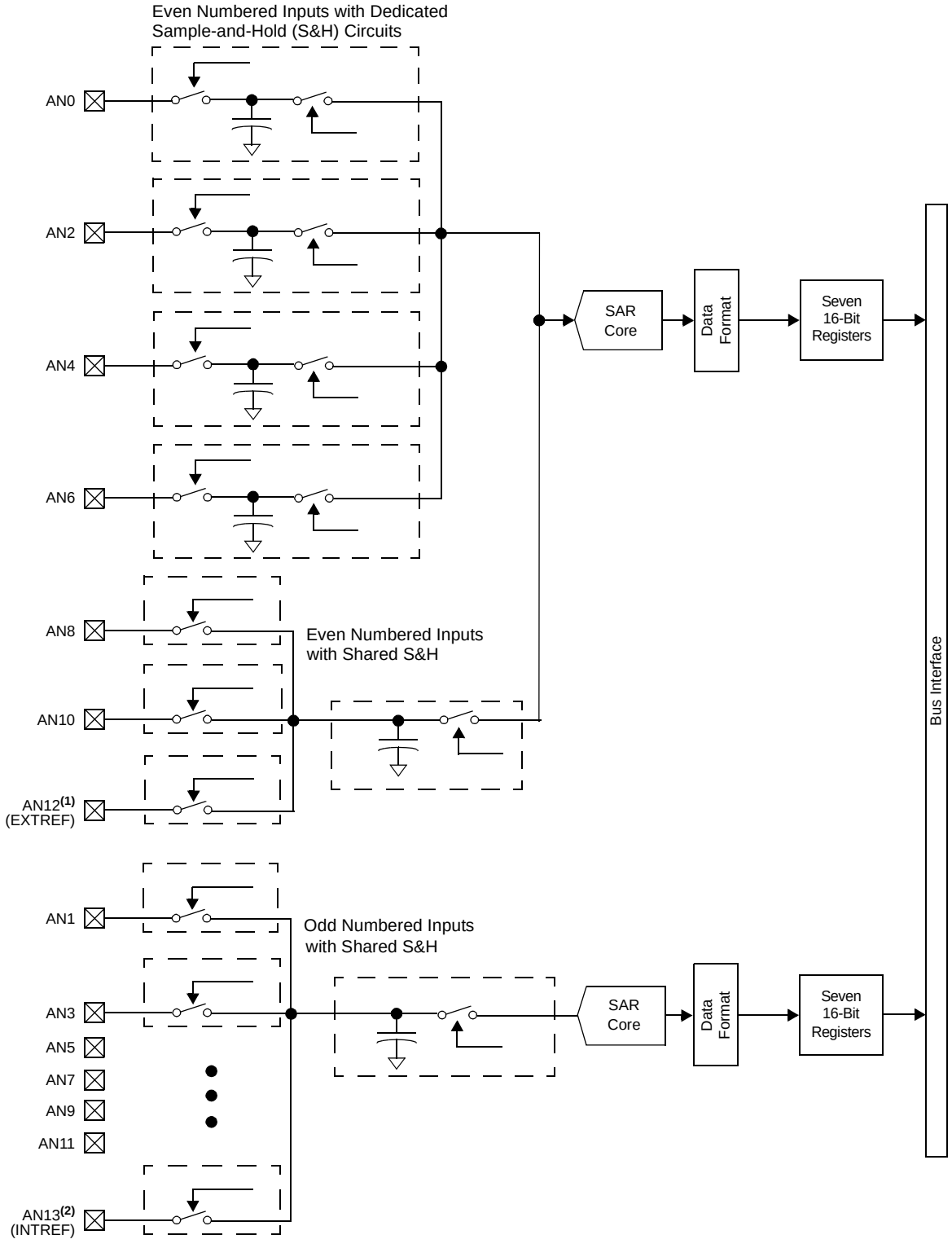
bit 4 **OCFLT:** PWM Fault Condition Status bit
1 = PWM Fault condition has occurred (cleared in hardware only)
0 = No PWM Fault condition has occurred (this bit is only used when OCM<2:0> = 111)

bit 3 **OCTSEL:** Output Compare Timer Select bit
1 = Timer3 is the clock source for Output Compare x
0 = Timer2 is the clock source for Output Compare x

bit 2-0 **OCM<2:0>:** Output Compare Mode Select bits
111 = PWM mode on OCx, Fault pin is enabled
110 = PWM mode on OCx, Fault pin is disabled
101 = Initializes OCx pin low, generates continuous output pulses on OCx pin
100 = Initializes OCx pin low, generates single output pulse on OCx pin
011 = Compare event toggles OCx pin
010 = Initializes OCx pin high, compare event forces OCx pin low
001 = Initializes OCx pin low, compare event forces OCx pin high
000 = Output compare channel is disabled

NOTES:

FIGURE 19-6: ADC BLOCK DIAGRAM FOR dsPIC33FJ16GS504 DEVICES WITH TWO SARS



Note 1: AN12 (EXTREF) is an internal analog input. To measure the voltage at AN12 (EXTREF), an analog comparator must be enabled and EXTREF must be selected as the comparator reference.

2: AN13 (INTREF) is an internal analog input and is not available on a pin.

TABLE 24-9: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
DI60a	IICL	**Input Low Injection Current**	0	—	-5(5,8)	mA	All pins except VDD, VSS, AVDD, AVSS, MCLR, VCAP and RB5
DI60b	IICH	**Input High Injection Current**	0	—	+5(6,7,8)	mA	All pins except VDD, VSS, AVDD, AVSS, MCLR, VCAP, RB5 and digital 5V-tolerant designated pins
DI60c	∑ IICT	**Total Input Injection Current (sum of all I/O and control pins)**	-20(9)	—	+20(9)	mA	Absolute instantaneous sum of all ± input injection currents from all I/O pins (| IICL + | IICH |) ≤ ∑ IICT

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: See **"Pin Diagrams"** for the list of 5V tolerant I/O pins.

5: VIL source < (VSS – 0.3). Characterized but not tested.

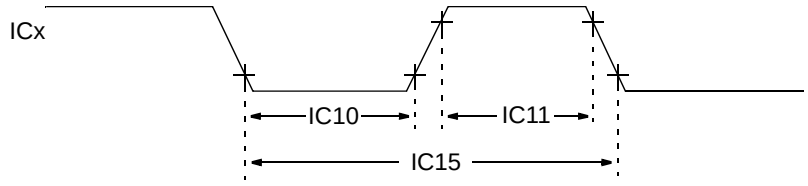
6: Non-5V tolerant pins VIH source > (VDD + 0.3), 5V tolerant pins VIH source > 5.5V. Characterized but not tested.

7: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.

8: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

9: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

FIGURE 24-6: INPUT CAPTURE x (ICx) TIMING CHARACTERISTICS



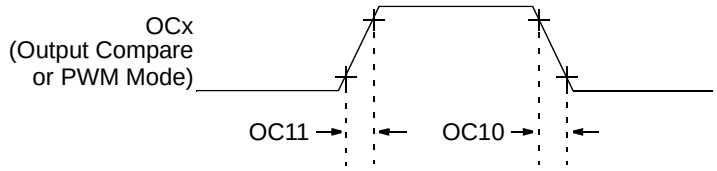
Note: Refer to Figure 24-1 for load conditions.

TABLE 24-26: INPUT CAPTURE x TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic(1)**		**Min**	**Max**	**Units**	**Conditions**
IC10	TccL	ICx Input Low Time	No prescaler	0.5 TCY + 20	—	ns	
			With prescaler	10	—	ns	
IC11	TccH	ICx Input High Time	No prescaler	0.5 TCY + 20	—	ns	
			With prescaler	10	—	ns	
IC15	TccP	ICx Input Period		(TCY + 40)/N	—	ns	N = Prescale value (1, 4, 16)

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 24-7: OUTPUT COMPARE x MODULE (OCx) TIMING CHARACTERISTICS



Note: Refer to Figure 24-1 for load conditions.

TABLE 24-27: OUTPUT COMPARE x MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
OC10	TccF	OCx Output Fall Time	—	—	—	ns	See Parameter DO32
OC11	TccR	OCx Output Rise Time	—	—	—	ns	See Parameter DO31

Note 1: These parameters are characterized but not tested in manufacturing.

TABLE 24-42: COMPARATOR MODULE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions (see Note 2): 3.0V to 3.6V Operating temperature: -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param. No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Comments**
CM10	VIOFF	Input Offset Voltage	-58	+14/-40	66	mV	
CM11	VICM	Input Common-Mode Voltage Range(1)	0	—	AVDD – 1.5	V	
CM12	VGAIN	Open Loop Gain(1)	90	—	—	db	
CM13	CMRR	Common-Mode Rejection Ratio(1)	70	—	—	db	
CM14	TRESP	Large Signal Response	21	30	49	ns	V+ input step of 100 mv while V- input held at AVDD/2. Delay measured from analog input pin to PWM output pin.

Note 1: Parameters are for design guidance only and are not tested in manufacturing.

2: Module is functional at VBOR < VDD < VDDMIN, but with degraded performance. Module functionality is tested but not characterized.

TABLE 24-43: DAC MODULE SPECIFICATIONS

AC and DC CHARACTERISTICS			Standard Operating Conditions (see Note 2): 3.0V to 3.6V Operating temperature: -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param. No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Comments**
DA01	EXTREF	External Voltage Reference(1)	0		AVDD – 1.6	V	
DA08	INTREF	Internal Voltage Reference(1)	1.25	1.32	1.41	V	
DA02	CVRES	Resolution		10		Bits	
DA03	INL	Integral Nonlinearity Error	-7	-1	+7	LSB	AVDD = 3.3V, DACREF = (AVDD/2)V
DA04	DNL	Differential Nonlinearity Error	-5	-0.5	+5	LSB	
DA05	EOFF	Offset Error	0.4	-0.8	2.6	%	
DA06	EG	Gain Error	0.4	-1.8	5.2	%	
DA07	TSET	Settling Time(1)	711	1551	2100	nsec	Measured when range = 1 (high range), and CMREF<9:0> transitions from 0x1FF to 0x300.

Note 1: Parameters are for design guidance only and are not tested in manufacturing.

2: Module is functional at VBOR < VDD < VDDMIN, but with degraded performance. Module functionality is tested but not characterized.

TABLE 25-9: SPIx MASTER MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	Symbol	Characteristic(1)	Min	Typ	Max	Units	Conditions
HSP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	10	25	ns	
HSP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	28	—	—	ns	
HSP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	35	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

TABLE 25-10: SPIx MODULE MASTER MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	Symbol	Characteristic(1)	Min	Typ	Max	Units	Conditions
HSP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	10	25	ns	
HSP36	TdoV2sc, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	35	—	—	ns	
HSP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	28	—	—	ns	
HSP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	35	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

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